DRAWING MADE IN THIRD ANGLE PROJECTION
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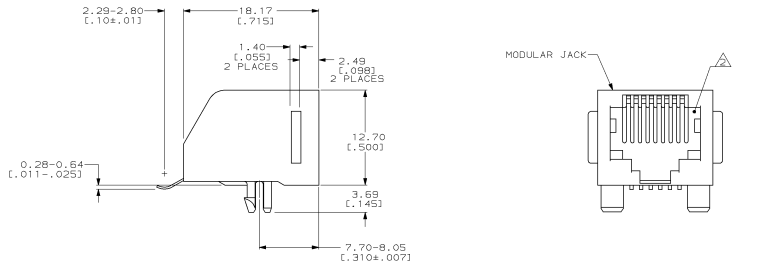
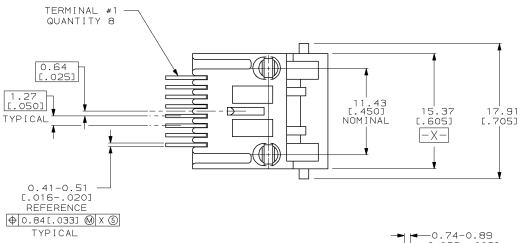
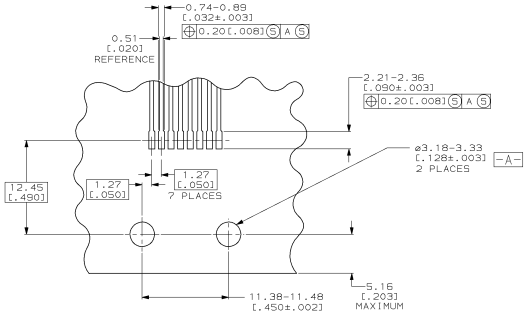
LOC	DIST	REVISIONS					
AA	22	ZONE	LTR	DESCRIPTION	DATE	APPD
			N	REV: EC 0502-0711-97	23OCT97	EL







RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT

1. MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 V0, BLACK.
   TERMINAL - 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.

8	555248-1
NUMBER OF TERMINALS	PART NO

DO NOT SCALE PRINT.
UNLESS SPECIFIED DIMENSIONS IN mm [INCHES]
TOLERANCES ON :
2 PLC DEC ± -
3 PLC DEC ± -
ANGLES ± -
MATERIAL
FINISH

DR 9-28-95 D. STRAUSSER
CHK 10-17-95 N. JONES
APPD 10-23-95 J. TONEY
APPD 10-24-95 M. MCGRATH
PRODUCT SPEC 108-1163
APPLICATION SPEC 114-6040
WEIGHT -

AMP Incorporated
Harrisburg, PA 17105-3608

NAME
MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, WITH PANEL STOPS

SIZE	CAGE CODE	DRAWING NO
D	00779	C-555248

SCALE 4:1 SHEET 1 OF 1

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CUSTOMER DRAWING

AMP 1766-3 REV 3-92
23-OCT-97 11:15:08 amp33741 /home/amp33741/edmmod
W45 87-1244-3-1 & -2

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